SN54390, SN54LS390, SN54393, SN54LS393 SN74390, SN74LS390, SN74393, SN74LS393 DUAL 4-BIT DECADE AND BINARY COUNTERS SDLS107 – OCTOBER 1976 – REVISED MARCH 1988

- Dual Versions of the Popular '90A, 'LS90 and '93A, 'LS93
- '390, 'LS390 . . . Individual Clocks for A and B Flip-Flops Provide Dual ÷ 2 and ÷ 5 Counters
- '393, 'LS393 . . . Dual 4-Bit Binary Counter with Individual Clocks
- All Have Direct Clear for Each 4-Bit Counter
- Dual 4-Bit Versions Can Significantly Improve System Densities by Reducing Counter Package Count by 50%
- Typical Maximum Count Frequency . . . 35 MHz
- Buffered Outputs Reduce Possibility of Collector Commutation

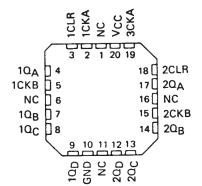
description

Each of these monolithic circuits contains eight master-slave flip-flops and additional gating to implement. two individual four-bit counters in a single package. The '390 and 'LS390 incorporate dual divide-by-two and divide-by-five counters, which can be used to implement cycle lengths equal to any whole and/or cumulative multiples of 2 and/or 5 up to divide-by-100. When connected as a bi-quinary counter, the separate divide-by-two circuit can be used to provide symmetry (a square wave) at the final

output stage. The '393 and 'LS393 each comprise two independent four-bit binary counters each having a clear and a clock input. N-bit binary counters can be implemented with each package providing the capability of divide-by-256. The '390, 'LS390, '393, and 'LS393 have parallel outputs from each counter stage so that any submultiple of the input count frequency is available for system-timing signals.

Series 54 and Series 54LS circuits are characterized for operation over the full military temperature range of -55° C to 125°C; Series 74 and Series 74LS circuits are characterized for operation from 0°C to 70°C. SN54390, SN54LS390 . . . J OR W PACKAGE SN74390 . . . N PACKAGE SN74LS390 . . . D OR N PACKAGE (TOP VIEW) 1CKA 15 2CKA 1CLR 2 1QA []3 14 2CLR 1CKB 13 20A 12 2CKB 1QB [] 5 11 🛛 20B 1QC [6 10 20C 10_D [] 7 GND 8 9 20D

> SN54LS390 . . . FK PACKAGE (TOP VIEW)



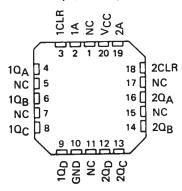
SN54393, SN54LS393 . . . J OR W PACKAGE SN74393 . . . N PACKAGE SN74LS393 . . . D OR N PACKAGE

(TOP VIEW)										
1A										
1CLR		13 2A								
10 _A		12 2CLF	2							
10 _B		11 2QA								
1QC	5	10 20B								
10 _D		9 20 C								

8] 2QD

SN54LS393 . . . FK PACKAGE (TOP VIEW)

GND 🗖 7



NC - No internal connection

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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BCD CO (EAC	'390, 'LS390 BCD COUNT SEQUENCE (EACH COUNTER) (See Note A)										
COUNT	OUTPUT										
COONT	٥D	QC	QB	QA							
0	L	L	L	L							
1	L	Ł	L	н							
2	L	L	н	L							
3	L	L	н	н							
4	L	н	L	L							
5	L	н	L	н							
6	L	н	н	L							
7	L	н	н	н							
8	н	L	E	L							
9	н	L	L	Н							

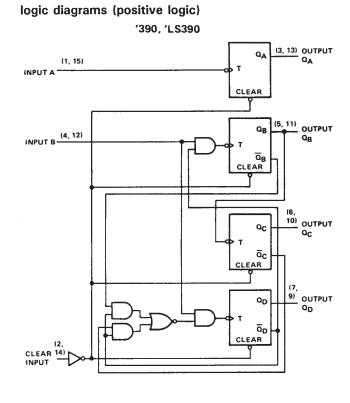
FUNCTION TABLES											
'390, 'LS390											
BI-C		ARY	(5-2	2)							
(EA	сн с	OUN	ITEF	()							
(See l	Vote	B)								
COLUNIT		ουτ	PUT								
COUNT QA QD QC QB											
OLLLL											
1	1 L L L H										
2	L	L	н	L							
3	L	L	н	н							
4	L	н	L	L							
5	н	L	L	L							
6	н	L	L	н							
7	н	L	Н	L							
8	н	L	н	н							
9	н	н	L	L							

COUNT SEQUENCE (EACH COUNTER) OUTPUT COUNT QB QA QD QC 0 L L L L н 1 L L L н L 2 L L 3 L L н н н L L 4 L 5 н L н L 6 L н н L н 7 н н L 8 н L L L 9 Н L Н L н L 10 н L 11 Н L н н 12 н н L L н н н L 13 14 н н н L. н н н н 15

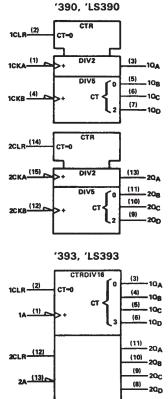
'393, 'LS393

NOTES: A. Output Q_A is connected to input B for BCD count. B. Output Q_D is connected to input A for bi-quinary count.

C. H = high level, L = low level.



logic symbols[†]

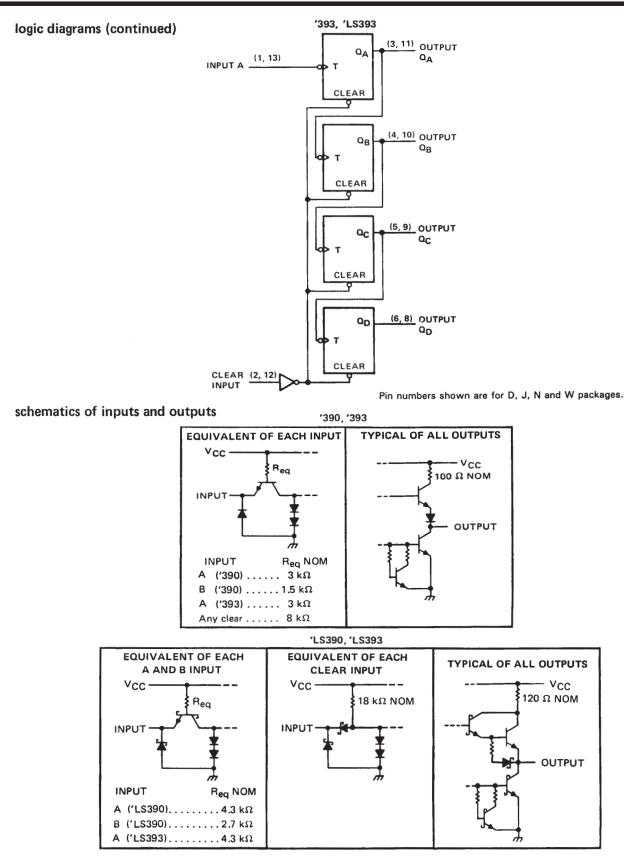


[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	
Input voltage	
Operating free-air temperature range: SN54390, SN54393	
	0°C to 70°C
	-65° C to 150° C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN5439 SN5439			SN7439 SN7439		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			·	-800			800	μA
Low-level output current, IOL				16			16	mA
Count from one f	A input	0		25	0		25	MHz
Count frequency, f _{count}	B input	0		20	0		20	
	A input high or low	20			20			
Pulse width, t _w	B input high or low	25			25			ns
	Clear high	20			20			1
Clear inactive-state setup time, t _{su}	÷	25			25↓			ns
Operating free-air temperature, TA		-55		125	0		70	°C

 \downarrow The arrow indicates that the falling edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETEO		TEST CON	DITIONS		′ 390			'393		
	PARAMETER		TEST CONI	DITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
ViH	High-level input voltage				2			2			V
VIL	Low-level input voltage						0.8			0.8	V
VIK	Input clamp voltage		V _{CC} = MIN, I	i ≖ –12 mA			-1.5			-1.5	V
v _{он}	High-level output voltage		V _{CC} = MIN, V V _{IL} = 0.8 V, I		2.4	3.4		2.4	3.4		v
VOL	Low-level output voltage		$V_{CC} = MIN, V_{IL} = 0.8 V, I_{e}$	/ _{1H} = 2 V,		0.2	0.4		0.2	0.4	v
11	Input current at maximum input voltage		V _{CC} = MAX, V	/ ₁ = 5.5 V			1			1	mA
		Clear					40			40	
Чн	High-level input current	Input A	V _{CC} = MAX, V	/1 = 2.4 V			80			80	μA
		Input B					120				
		Clear					1			-1	
hL	Low-level input current	Input A	V _{CC} = MAX, V	/ i = 0.4 V			-3.2			-3.2	mA
		Input B					-4.8				
1	Chart airquit autnut aurrant 8		Vee - MAX	SN54'	-20		57	-20		-57	mA
los	Short-circuit output current §		V _{CC} = MAX	SN74'	-18		-57	-18		-57	
ICC	Supply current		V _{CC} = MAX, S	iee Note 2		42	69		38	64	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25 °C.

§ Not more than one output should be shorted at a time.

The Q_A outputs of the '390 are tested at I_{OL} = 16 mA plus the limit value for I_{IL} for the B input. This permits driving the B input while maintaining full fan-out capability.

NOTE 2: I_{CC} is measured with all outputs open, both clear inputs grounded following momentary connection to 4.5 V, and all other inputs grounded.



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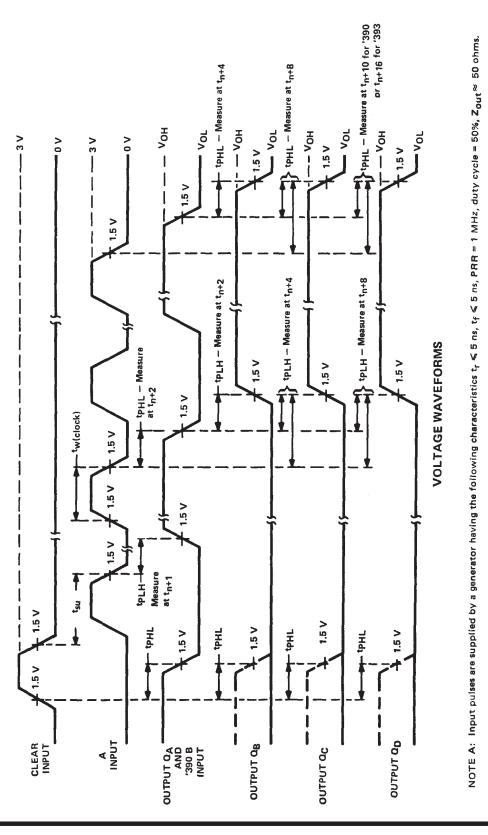
	FROM	TO	TEAT CONDITIONS		'390			' 393		UNIT
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	MIN	түр	MAX	UNIT
	А	QA		25	35		25	35		MHz
fmax	В	QB		20	30					141112
tplH		0]		12	20		12	20	ns
^t PHL	A	QA			13	20		13	20	113
^t PLH		Q _C of '390	C _L = 15 pF,		37	60		40	60	ns
^t PHL.	A	Q _D of '393	R _L = 400 Ω,		39	60		40	60	113
^t PLH		0	See Note 3		13	21				ns
tPHL	В	QB	and		14	21				115
tpLH	в	0.	Figure 1		24	39				ns
^t PHL		α _c			26	39				
tPLH	в	0-]		13	21				ns
^t PHL		۵ _D			14	21				113
tPHL	Clear	Any]		24	39		24	39	ns

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



SN54390, SN54LS390, SN54393, SN54LS393 SN74390, SN74LS390, SN74393, SN74LS393 DUAL 4-BIT DECADE AND BINARY COUNTERS SDLS107 - OCTOBER 1976 - REVISED MARCH 1988



PARAMETER MEASUREMENT INFORMATION

FIGURE 1



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	
Clear input voltage	
Any A or B clock input voltage	
Operating free-air temperature range: SN54LS390, SN54LS393	-55° C to 125° C
SN74LS390, SN74LS393	3 0°C to 70°C
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		-	N54LS3 N54LS3			N74LS3 N74LS3		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH	······································			-400			-400	μA
Low-level output current, IOL				4			8	mA
0	A input	0		25	0		25	MHz
Count frequency, f _{count}	B input	0		12.5	0		12.5	IVIF12
and an obligation from the statement	A input high or low	20			20			
Pulse width, t _w	B input high or low	40			40			ns
	Clear high	20			20]
Clear inactive-state setup time, t _{su}	······································	25‡			25↓			ns
Operating free-air temperature, TA		55		125	0		70	°C

¹ The arrow indicates that the falling edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

							SN54L	5'		SN74L	S'	UNIT
	PARAMETER		TEST CONDITIONS [†]				түр‡	MAX	MIN	түр‡	MAX	UNIT
VIH	High-level input voltage					2			2			V
VIL	Low-level input voltage							0.7			0.8	V
VIK	Input clamp voltage		V _{CC} = MIN,	l _l = –18 mA				-1.5			-1.5	V
v _{он}	High-level output voltage		V _{CC} = MIN, VIL = VILmax,	$V_{\rm IH} = 2 V,$ $I_{\rm OH} = -400 \ \mu A$		2.5	3.4		2.7	3.4		v
	1		V _{CC} = MIN,	VIH = 2 V,	IOL = 4 mA¶		0.25	0.4		0.25	0.4	v
VOL	Low-level output voltage		V _{IL} = 0.8 V,		10L = 8 mA¶					0.35	0.5	
		Clear			V ₁ = 7 V			0.1			0.1	
lη –	Input current at maximum input voltage	Input A	V _{CC} = MAX		V1 = 5.5 V			0.2			0.2	mA
	maximum input vortage	Input B			V1 - 5.5 V			0.4			0.4	
		Clear						0.02			0.02	1
Чн	High-level input current	Input A	V _{CC} = MAX,	V _I = 2.7 V				0.1			0.1	mA
		Input B						0.2			0.2	
[Clear						-0.4			0.4	1
41	Low-level input current	Input A	V _{CC} = MAX,	V ₁ = 0.4 V				-1.6			-1.6	mA
		Input B						-2.4			-2.4	L
IOS	Short-circuit output cur	rent§	V _{CC} = MAX			-20		-100	-20		-100	mA
	Currely evenent		V _{CC} = MAX,		'LS390		15	26		15		mA
1 cc	Supply current		See Note 2		'LS393		15	26		15	26	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 V$, $T_A = 25 °C$.

§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

The QA outputs of the 'LS390 are tested at IOL = MAX plus the limit value for IIL for the clock B input. This permits driving the clock B input while maintaining full fan-out capability.

NOTE 2: ICC is measured with all outputs open, both clear inputs grounded following momentary connection to 4.5 V, and all other inputs grounded.



SN54390, SN54LS390, SN54393, SN54LS393 SN74390, SN74LS390, SN74393, SN74LS393 DUAL 4-BIT DECADE AND BINARY COUNTERS SDLS107 - OCTOBER 1976 - REVISED MARCH 1988

switching characteristics, V_{CC} = 5 V, $T_A = 25^{\circ}C$

DADAMETED	FROM	то			'LS390			'LS393		
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	MIN	түр	MAX	UNIT
£	A	QA		25	35		25	35		MHz
f _{max}	В	QB]	12.5	20					WHZ
^t PLH	A	0.			12	20		12	20	
^t ₽HL	1 ^	QA			13	20		13	20	ns
^t PLH	A	Q _C of 'LS390	C _L = 15 pF,		37	60		40	60	
^t PHL		Q _D of 'LS393	$R_{L} = 2 k\Omega,$		39	60		40	60	ns
^t PLH	в	0-	See Note 4 and Figure 2		13	21				
^t PHL	1 ^D	α _B			14	21				ns
^t PLH	в	0.5			24	39				
^t ₽HL	1	α _C			26	39				ns
^t PLH	в	0-			13	21				
^t PHL		٥D			14	21				ns
^t ₽HL	Clear	Any			24	39		24	39	ns

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.



PARAMETER MEASUREMENT INFORMATION

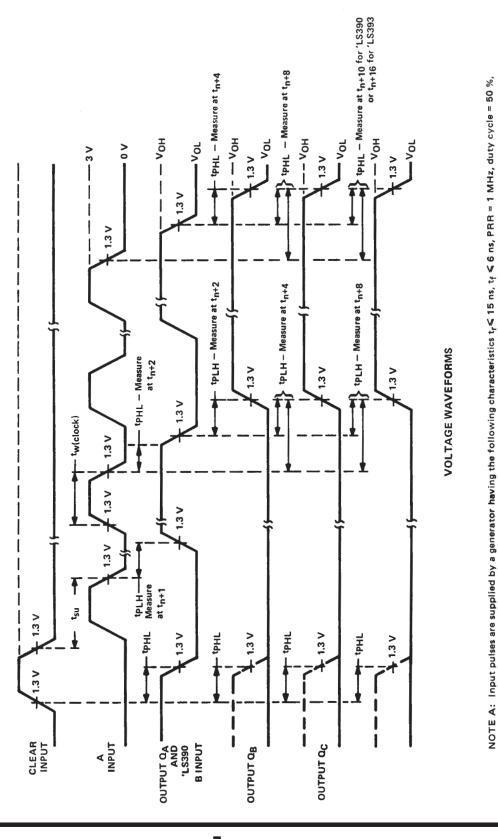


FIGURE 2

 $Z_{out} \approx 50 \text{ ohms.}$





25-Sep-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
7802601EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601EA SNJ54LS390J	Samples
7802601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples
7802601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples
JM38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Samples
JM38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Samples
JM38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Samples
JM38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Samples
JM38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Samples
JM38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Samples
JM38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Samples
JM38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Samples
JM38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samples
JM38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samples
JM38510/32702SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SCA SNV54LS393J	Samples
JM38510/32702SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SCA SNV54LS393J	Samples
JM38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SDA SNV54LS393W	Samples



Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
JM38510/32702SDA	(1) ACTIVE	CFP	W	14	25	(2) TBD	A42	⁽³⁾ N / A for Pkg Type	-55 to 125	(4/5) JM38510/ 32702SDA SNV54LS393W	Sample
M38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Sample
M38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Sampl
M38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Sampl
M38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Sampl
M38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Sampl
M38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Sampl
M38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Samp
M38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Sampl
M38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samp
M38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samp
M38510/32702SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SCA SNV54LS393J	Samp
M38510/32702SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SCA SNV54LS393J	Samp
M38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SDA SNV54LS393W	Samp
M38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SDA SNV54LS393W	Samp
SN54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SN54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		



Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Sam
SN54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS390J	Sam
SN54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS390J	Sam
SN54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS393J	Sam
SN54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS393J	San
SN74390N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74390N	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	0 to 70		
SN74393N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74393N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74393N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		
SN74393N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		
SN74LS390D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	San
SN74LS390D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	San
SN74LS390DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	San
SN74LS390DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	Sar
SN74LS390DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	Sar
SN74LS390DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	Sar
SN74LS390N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	San
SN74LS390N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	Sar
SN74LS390N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS390N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS390NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	Sar
SN74LS390NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	Sar



Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
SN74LS390NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS390	Sample
SN74LS390NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS390	Sample
SN74LS390NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS390	Sample
SN74LS390NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS390	Sample
SN74LS390NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS390	Sample
SN74LS390NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS390	Sample
SN74LS393D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample
SN74LS393D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample
SN74LS393DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample
SN74LS393DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample
SN74LS393DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample
SN74LS393DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample
SN74LS393DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample
SN74LS393DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample
SN74LS393DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample
SN74LS393DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample
SN74LS393DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample
SN74LS393DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Sample



Orderable Device		Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
SN74LS393J	(1) OBSOLETE	CDIP	J	14	aty	(2) TBD	Call TI	(3) Call TI	0 to 70	(4/5)	
SN74LS393J	OBSOLETE	-	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS3935	ACTIVE	PDIP	N	14	25	Pb-Free	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Sample
						(RoHS)					Sample
SN74LS393N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Sample
SN74LS393N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	0 to 70		
SN74LS393N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS393NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Sample
SN74LS393NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Sample
SN74LS393NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS393	Sample
SN74LS393NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS393	Sampl
SN74LS393NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS393	Sampl
SN74LS393NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS393	Sampl
SN74LS393NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS393	Sampl
SN74LS393NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS393	Sampl
SNJ54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SNJ54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SNJ54393W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		
SNJ54393W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS390FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 390FK	Sampl
SNJ54LS390FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 390FK	Sampl
SNJ54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601EA SNJ54LS390J	Sampl



25-Sep-2013

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
SNJ54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601EA SNJ54LS390J	Samples
SNJ54LS390W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples
SNJ54LS390W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples
SNJ54LS393FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 393FK	Samples
SNJ54LS393FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 393FK	Samples
SNJ54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393J	Samples
SNJ54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393J	Samples
SNJ54LS393W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393W	Samples
SNJ54LS393W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



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(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54393, SN54LS390, SN54LS393, SN54LS393-SP, SN74393, SN74LS390, SN74LS393 :

- Catalog: SN74393, SN74LS390, SN74LS393, SN54LS393
- Military: SN54393, SN54LS390, SN54LS393
- Space: SN54LS393-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE AND REEL INFORMATION

TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

*All dimensions are nomina	I											
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS390NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS393DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS393NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS390NSR	SO	NS	16	2000	367.0	367.0	38.0
SN74LS393DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS393NSR	SO	NS	14	2000	367.0	367.0	38.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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